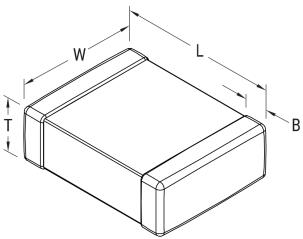


CBR06C360F5GAC

CBR-SMD RF COG, Ceramic, 36 pF, 1%, 50 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0603



Click here for the 3D model.

| Dimensions | |
|------------|-----------------|
| Chip Size | 0603 |
| L | 1.6mm +/-0.1mm |
| W | 0.8mm +/-0.1mm |
| Т | 0.8mm +/-0.07mm |
| В | 0.4mm +/-0.15mm |

| Packaging Specifications | |
|--------------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 4000 |

| CBR-SMD RF COG |
|---|
| SMD Chip |
| SMD, Fixed, RF, Ultra High Q, Low ESR, Class I |
| Ultra High Q, Low ESR, Class I |
| Yes |
| Tin |
| No |
| No |
| 5.29 mg |
| Solder Wave or Solder Reflow. |
| 78 Weeks |
| 1 |
| |

| Specifications | |
|---------------------------------|---------------------|
| Capacitance | 36 pF |
| Capacitance Tolerance | 1% |
| Voltage DC | 50 VDC |
| Dielectric Withstanding Voltage | 125 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | COG |
| Dissipation Factor | O.1% |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 10 GOhms |
| Quality Factor | 1000 |

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